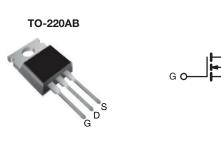
Vishay Siliconix



E Series Power MOSFET

PRODUCT SUMMARY						
V _{DS} (V) at T _J max.	700					
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.6				
Q _g max. (nC)	48					
Q _{gs} (nC)	6					
Q _{gd} (nC)	11					
Configuration	Single					



S N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

OORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP6N65E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-Source Voltage			V _{DS}	650	V		
Gate-Source Voltage			V _{GS}	± 30			
Continuous Drain Current (T. 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	7			
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		5	А		
Pulsed Drain Current ^a			I _{DM}	18	1		
Linear Derating Factor				0.63	W/°C		
Single Pulse Avalanche Energy ^b			E _{AS}	56	mJ		
Maximum Power Dissipation			P _D	78	W		
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	T _J = 125 °C		d\//dt	37	1//22		
Reverse Diode dV/dt ^d			dV/dt	27	V/ns		
Soldering Recommendations (Peak Temperature) ^c	for	10 s		300	°C		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 28.2 mH, $R_g = 25 \Omega$, $I_{AS} = 2$ A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

1 For technical questions, contact: <u>hvm@vishay.com</u>



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THERMAL RESISTANCE RAT	INGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	- 62 - 1.6					
Maximum Junction-to-Case (Drain)	R _{thJC}	-				- °C/W		
SPECIFICATIONS (T _J = 25 $^{\circ}$ C,	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static						•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D =	250 µA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.73	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V_{GS} , I_D =	250 µA	2	-	4	V
Cata Sauraa Laakaga		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
Zara Cata Valtaga Drain Current	$V_{DS} = 650 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_S = 0 V	-	-	1			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 520 \	$V_{\rm GS} = 0$	/, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$		I _D = 3 A	-	0.5	0.6	Ω
Forward Transconductance	g _{fs}	V _{DS}	_s = 30 V, I _D	= 3 A	-	2	-	S
Dynamic	•						•	•
Input Capacitance	C _{iss}		V _{GS} = 0 V		-	820	-	
Output Capacitance	C _{oss}	$V_{DS} = 100 V,$ f = 1 MHz $V_{DS} = 0 V to 520 V, V_{GS} = 0 V$		-	40	-	рF	
Reverse Transfer Capacitance	C _{rss}			-	4	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	36	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	117	-		
Total Gate Charge	Qg				-	24	48	1
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 3 \text{ A}, V_{DS} = 520 \text{ V}$		-	6	-	nC	
Gate-Drain Charge	Q _{gd}			-	11	-		
Turn-On Delay Time	t _{d(on)}				-	14	28	
Rise Time	t _r	Vaa	= 520 V, I _D	- 3 A	-	12	24	ns
Turn-Off Delay Time	t _{d(off)}		= 10 V, R _q :		-	30	60	
Fall Time	t _f			-	20	40		
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	1.4	-	Ω	
Drain-Source Body Diode Characterist	ics	•				•	•	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	A	
Pulsed Diode Forward Current	I _{SM}			-	-	18		
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 3 A, V _{GS} = 0 V			-	-	1.3	V
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C, } I_{F} = I_{S} = 3 \text{ A,}$ dI/dt = 100 A/µs, V _R = 25 V		-	237	-	ns	
Reverse Recovery Charge	Q _{rr}			-	2.2	-	μC	
Reverse Recovery Current	I _{RRM}			-	16	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

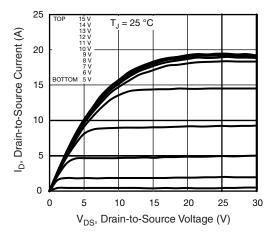


Fig. 1 - Typical Output Characteristics

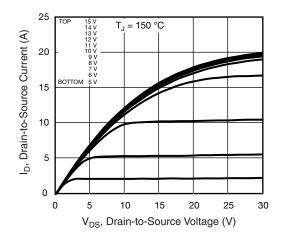


Fig. 2 - Typical Output Characteristics

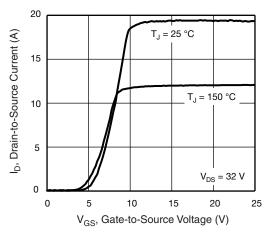


Fig. 3 - Typical Transfer Characteristics

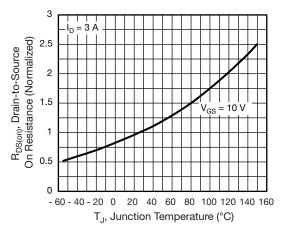


Fig. 4 - Normalized On-Resistance vs. Temperature

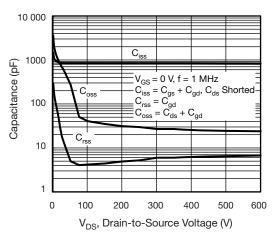


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

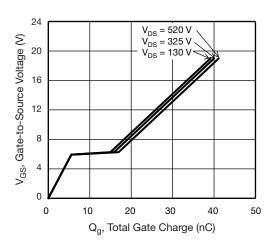


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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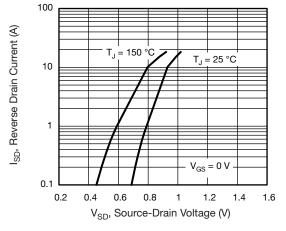


Fig. 7 - Typical Source-Drain Diode Forward Voltage

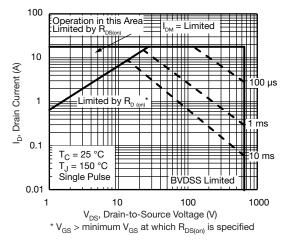


Fig. 8 - Maximum Safe Operating Area

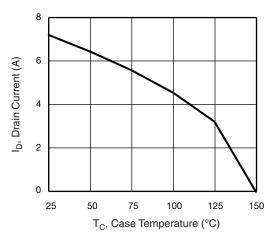


Fig. 9 - Maximum Drain Current vs. Case Temperature

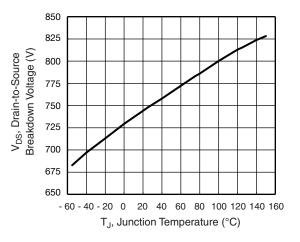
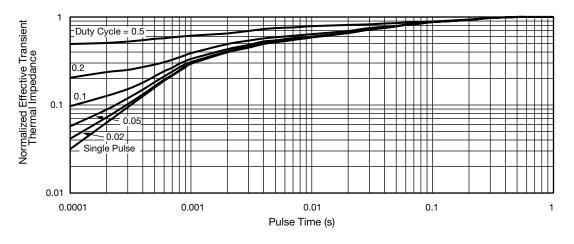


Fig. 10 - Temperature vs. Drain-to-Source Voltage





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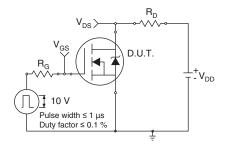


Fig. 12 - Switching Time Test Circuit

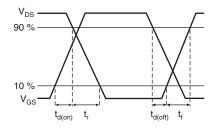


Fig. 13 - Switching Time Waveforms

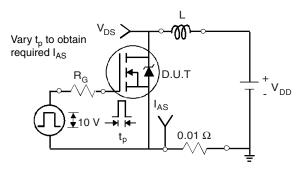


Fig. 14 - Unclamped Inductive Test Circuit

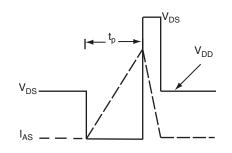


Fig. 15 - Unclamped Inductive Waveforms

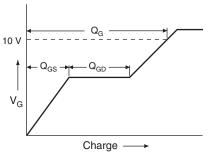


Fig. 16 - Basic Gate Charge Waveform

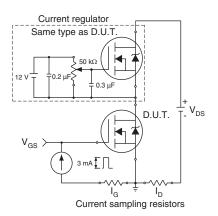


Fig. 17 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit

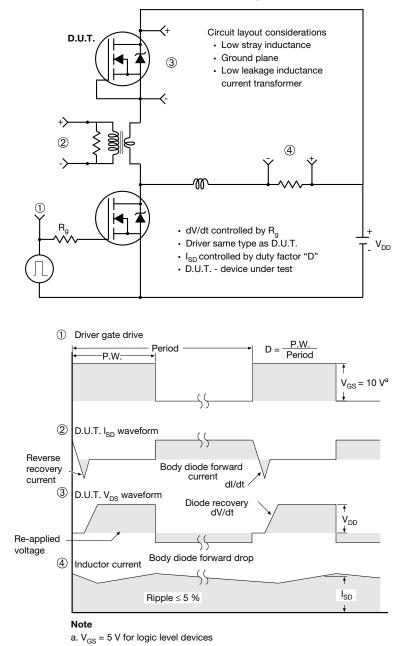


Fig. 18 - For N-Channel

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